

This listing of claims will replace all prior versions, and listings, of claims in the application.

LISTING OF THE CLAIMS:

Claims 1-12 (Cancelled).

Claim 13. (Currently Amended) A ~~high-strength~~ laminate structural support in a wire-bonded circuit device in large-scale integrated circuitry, wherein said laminate support is of a strength to resist the circuitry to deform, in which said circuit device comprises a circuit pad of a large scale integrated design arranged on a substrate whereby said pad exhibits a tendency to collapse due to detrimental interaction of wire thickness, copper hardness, pad thickness, processing tool pressure and material construction of the laminate support, comprising:

said substrate being a closed woven mesh structure having a first surface supporting said circuit device; and

a wire being positioned on said first surface of said substrate, said closed woven mesh structure of the substrate having a thickness of between about 2.5 and 4.0 mils and being constituted of fiberglass having strands possessing separation distances which are equal to or less than a cross-sectional diameter of said wire positioned on said first surface of said substrate, said separation distances between said strands being within the range of about 0.2 to 0.7 mils so as to prevent deformation and

collapse of said circuit device in response to wire bonding, said closed woven mesh structure of said substrate being constituted of fiberglass having warp and weave strands, having separation distances equal to or less than the thickness of said wire on said first surface of said substrate, as measured lengthwise through said closed woven mesh.

Claim 14. (Cancelled).